

### **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the present application.

#### **Listing of Claims:**

**Claim 1 (currently amended):** A wafer holder for semiconductor manufacturing ~~device~~ equipment, the wafer holder having a wafer-carrying surface for carrying wafers, the wafer-carrying surface having a planarity of 0.5 mm or less and comprising multiple nubs formed thereon ~~on the wafer-carrying surface~~, said nubs each having a flat portion whose surface area is  $70 \text{ mm}^2$  or less per nub, wherein the total surface area of the flat portions of said multiple nubs is 40% or less of the surface area of wafers that the wafer holder carries.

**Claim 2 (canceled)**

**Claim 3 (currently amended):** Semiconductor manufacturing ~~device~~ equipment wherein the wafer holder set forth in claim 1 is installed.

**Claim 4 (canceled)**

**Claim 5 (currently amended):** A wafer holder for semiconductor manufacturing ~~device~~ equipment, the wafer holder having a wafer-carrying surface for carrying wafers and comprising multiple nubs formed on the wafer-carrying surface and each having a flat portion, the total surface area of the flat portions of said multiple nubs being 40% or less of the surface area of wafers that the wafer holder carries, the wafer-carrying surface having a planarity of 0.5 mm or less.

**Claim 6 (original):** Semiconductor manufacturing device wherein the wafer holder set forth in claim 5 is installed.